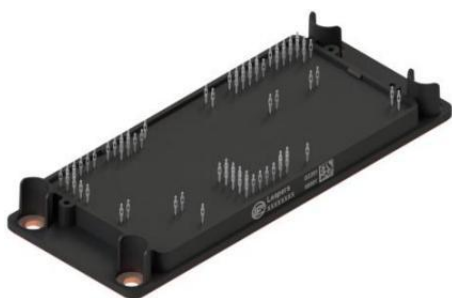


Description

The DFH300AL12E4C1 is a 3-level Power Module. It integrates 1200V SiC MOSFET chips and 1200V IGBT chips designed for the applications such as Solar Inverter, High frequency switching, Energy storage Systems etc.



Features

- Blocking voltage:1200V
- $R_{ds(on)}$: 4.3m Ω @ V_{GS} =18V
- Low Switching Losses
- High current density
- Press FIT Contact Technology
- 175 °C maximum junction temperature
- Thermistor inside

Applications

- Solar inverter Systems
- Three-level applications
- Energy Storage Systems
- High Frequency Switching application

Circuit diagram

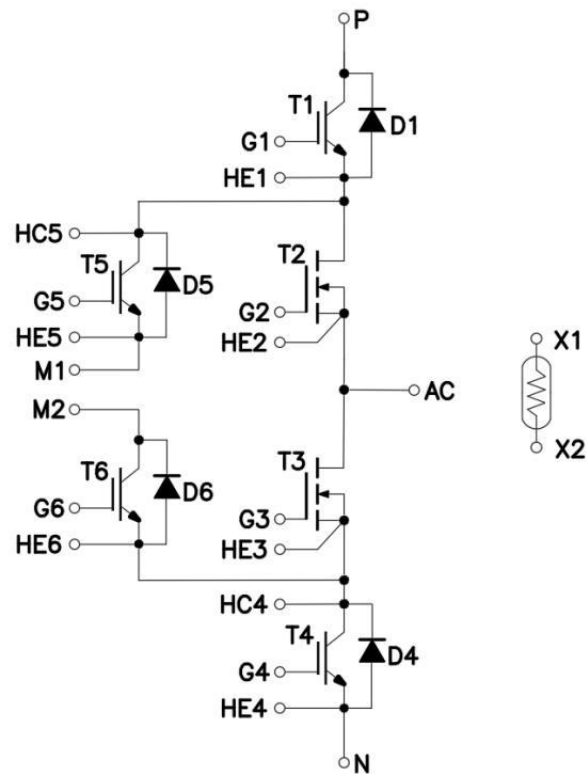


Figure 1. Out drawing & circuit diagram for DFH300AL12E4C1

Pin Configuration

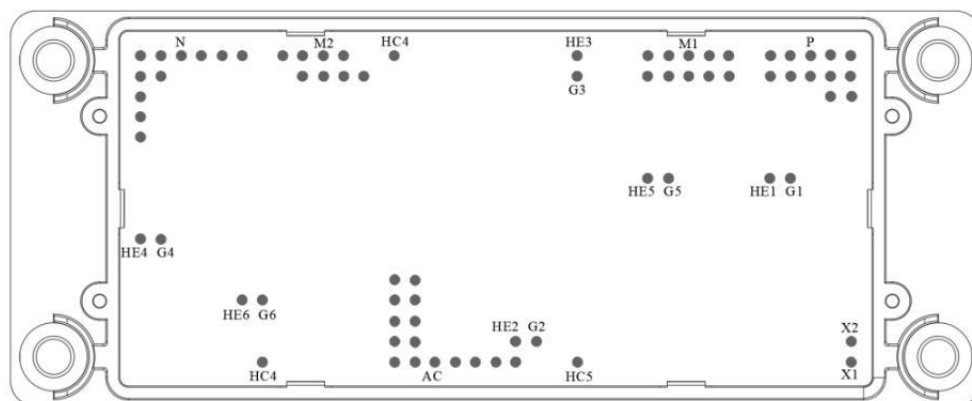


Figure 2. Pin configuration

Module

Parameter	Conditions	Value	Unit
Isolation voltage	Main terminal to base plate, RMS, f =50Hz, t =1 min	3.4	kV
Creepage distance	terminal to heatsink	11.2	mm
	terminal to terminal	6.8	
Clearance	terminal to heatsink	9.4	
	terminal to terminal	5.5	
Comparative tracking index	-	> 400	
Mounting torque for module mounting	Screw M5 baseplate to heatsink	1.3 to 1.5	Nm
Storage temperature	-	-40 to 125	°C
Weight	-	125	g

NTC characteristics

Symbol	Parameter	Condition	Value			Unit
			Min.	Typ.	Max.	

R ₂₅	Resistance	T _C =25°C	-	5	-	kΩ
ΔR/R	Deviation of R100	T _C =100°C, R ₁₀₀ =493Ω	-5	-	5	%
P ₂₅	Power dissipation	T _C =25°C	-	-	20	mW
B _{25/50}	B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3375	-	K
B _{25/80}	B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3411	-	K
B _{25/100}	B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3433	-	K

Maximum Ratings (T2/T3: SiC MOSFET, $T_j=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
V_{DSS}	Drain-Source Voltage	G-S Short	1200	V
V_{GSS}	G-S Voltage	D-S Short, Note1	-8 to 22	V
I_{DS}	DC Continuous Drain Current	$T_s=65^{\circ}\text{C}$	275	A
I_{SD}	Source (Body diode) Current	-	275	A
I_{DP}	Drain Pulse Current, Peak	Less than 1ms, Note2	600	A
T_j	junction temperature	-	-40 to 175	$^{\circ}\text{C}$

Note1: Recommended Operating Value, +18V/-4V, +15V/-4V

Maximum Ratings (T1/T4/T5/T6: IGBT, $T_j=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
V_{CES}	Collector-Emitter Voltage	G-E Short	1200	V
V_{GES}	Gate-Emitter Voltage	C-E Short	± 20	V
I_{CDC}	DC Continuous Collector Current	$T_s=65^{\circ}\text{C}$, $T_j=150^{\circ}\text{C}$	310	A
I_{CM}	Pulse Collector Current	$t_p=1\text{ms}$, Note1	800	A
P_{C}	Maximum Power Dissipation	$T_c=25^{\circ}\text{C}$, $T_j=175^{\circ}\text{C}$	1136	W
T_j	junction temperature	-	-40 to 175	$^{\circ}\text{C}$

Note1: Pulse width limited by maximum junction temperature

Maximum Ratings (D1/D4/D5/D6: Diode, $T_j=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
V_{RRM}	Repetitive peak reverse Voltage	G-E Short	1200	V
I_{F}	Diode forward Current	-	300	A
I_{FRM}	Repetitive peak forward Current	$t_p=1\text{ms}$, Note1	600	A
T_j	junction temperature	-	-40 to 175	$^{\circ}\text{C}$

Note1: Pulse width limited by maximum junction temperature

Preliminary datasheet _Ver.A EN

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T2/T3: SiC MOSFET Electrical characteristics (T_j=25°C unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =400uA		1200	-	-	V
I _{DSS}	Zero gate voltage drain Current	V _{DS} =1200V, V _{GS} =0V		-	-	400	μA
V _{GS(th)}	Gate-source threshold Voltage	I _D =80mA, V _{DS} =V _{GS}		1.9	2.6	3.5	V
I _{GSS}	Gate-Source Leakage Current	V _{GS} =18V, V _{DS} =0V		-	-	400	nA
R _{DS(on)} (Chip)	Static drain-source On-state resistance	I _D =300A V _{GS} =18V	T _j =25°C	-	4.3	7.5	mΩ
			T _j =175°C	-	8.0	-	mΩ
V _{DS(on)} (Chip)	Static drain-source On-state Voltage	I _D =300A V _{GS} =18V	T _j =25°C	-	1.29	2.25	V
			T _j =175°C	-	2.40	-	V
C _{iss}	Input Capacitance	V _D =1000V, V _{GS} =0V f =1MHz		-	18.8	-	nF
C _{oss}	Output Capacitance			-	0.8	-	nF
C _{rss}	Reverse transfer Capacitance			-	0.08	-	nF
Q _G	Total gate charge	V _{DD} =800V, I _D =200A, V _{GS} =0/+18V		-	860	-	nC
R _{Gint}	Internal Gate Resistance	f =1Mhz, V _{AC} =25mV		-	0.15	-	Ω
t _{d(on)}	Turn-on delay time	V _{CC} =600V I _D =300A V _{GS} =+15V/-4V R _g =5.0Ω Inductive load switching operation	T _j =25°C	-	37	-	ns
			T _j =150°C	-	36	-	
t _r	Rise time		T _j =25°C	-	48	-	ns
			T _j =150°C	-	50	-	
t _{d(off)}	Turn-off delay time		T _j =25°C	-	82	-	ns
			T _j =150°C	-	87	-	
t _f	Fall time		T _j =25°C	-	25	-	ns
			T _j =150°C	-	26	-	
E _{on}	Turn-on power dissipation		T _j =25°C	-	6.75	-	mJ
			T _j =150°C	-	8.74	-	
E _{off}	Turn-off power dissipation		T _j =25°C	-	2.89	-	mJ
			T _j =150°C	-	3.59	-	
R _{th(j-c)}	FET Thermal Resistance	Junction to Case/MOSFET		-	0.082	-	K/W

$R_{th(c-s)}$	Thermal Resistance, Case to sink (Conductive Grease applied) , Note1	-	0.10	-	K/W
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Note1: Assumes Thermal Conductivity of grease is 2.8W/m·K and thickness is 50um.

T2/T3: Body Diode Electrical characteristics (T_j=25°C unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
V _{SD}	Body Diode Forward Voltage	V _{GS} =-4V I _{SD} =300A	T _j =25°C	-	5.0	-	V
			T _j =175°C	-	3.9	-	
T _{rr}	Reverse recovery time	V _{CC} =600V I _D =300A	T _j =25°C	-	34	-	ns
			T _j =150°C	-	48	-	
Q _{rr}	Reverse recovery charge	V _{GS} =+15/-4V R _g =5.0Ω	T _j =25°C	-	0.69	-	μC
			T _j =150°C	-	2.02	-	
E _{rr}	Diode switching power dissipation	Inductive load switching operation	T _j =25°C	-	0.67	-	mJ
			T _j =150°C	-	1.06	-	

T1/T4/T5/T6: IGBT Electrical characteristics ($T_j=25^\circ\text{C}$ unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
V _{CE(sat)} (Chip)	Collector-Emitter Saturation Voltage	I _C =300A V _{GE} =15V	T _j =25°C	-	1.65	-	V
			T _j =150°C	-	1.85	-	V
			T _j =175°C	-	1.90	-	V
V _{GE(th)}	Gate-Emitter threshold Voltage	I _C =11.4mA, V _{CE} =V _{GE}		5.0	5.6	6.8	V
Q _G	Gate charge	V _{GE} =-15V to +15V		-	2.2	-	uC
R _{Gint}	Internal gate resistor	-	T _j =25°C	-	2.5	-	Ω
C _{ies}	Input Capacitance	V _{CE} =25V, V _{GE} =0V f =1MHz	T _j =25°C	-	26.0	-	nF
C _{res}	Reverse transfer Capacitance			-	0.93	-	nF
I _{CES}	Collector- Emitter Cut off Current	V _{CE} =1200V, V _{GE} =0V	T _j =25°C	-	-	1	mA
I _{GES}	Gate-Emitter Leakage Current	V _{GE} =20V, V _{CE} =0V	T _j =25°C	-	-	0.75	uA
t _{d(on)}	Turn-on delay time	V _{CC} =600V I _C = 300A V _{GE} =+15V/-8V R _g =1.0Ω Inductive load	T _j =25°C	-	168	-	ns
			T _j =125°C	-	171	-	
			T _j =175°C	-	179	-	
t _r	Rise time		T _j =25°C	-	44	-	ns
			T _j =125°C	-	47	-	
			T _j =175°C	-	48	-	
t _{d(off)}	Turn-off delay time		T _j =25°C	-	392	-	ns
			T _j =125°C	-	421	-	
			T _j =175°C	-	449	-	
t _f	Fall time		T _j =25°C	-	90	-	ns
			T _j =125°C	-	129	-	
			T _j =175°C	-	159	-	
E _{on}	Turn-on power dissipation		T _j =25°C	-	25.1	-	mJ
			T _j =125°C	-	33.2	-	
			T _j =175°C	-	38.7	-	
				T _j =25°C	-	21.3	-

E _{off}	Turn-off power dissipation		T _j =125°C	-	29.4	-	mJ
			T _j =175°C	-	35.7	-	
R _{th(j-c)}	Thermal Resistance, Junction to Case (IGBT)			-	0.032	-	K/W
R _{th(c-s)}	Thermal Resistance, Case to sink (Conductive Grease applied) , Note1			-	0.10	-	K/W

Note1 : Assumes Thermal Conductivity of grease is 2.8 W/m · K and thickness is 50 um.

D1/D4/D5/D6: Freewheeling Diode Electrical characteristics ($T_j=25^{\circ}\text{C}$ unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
V _F	Diode Forward Voltage	I _F =300A, V _{GE} =0V	T _j =25°C	-	1.7	2.1	V
			T _j =175°C	-	1.65	-	
t _{rr}	Reverse recovery time	(Switch side) V _{CC} =600V I _C =300A V _{GE} = +15V/-8V R _g =1.0Ω (FRD side)	T _j =25°C	-	0.30	-	us
			T _j =125°C	-	0.57	-	
			T _j =175°C	-	0.66	-	
I _{RM}	Peak reverse recovery Current		T _j =25°C	-	280	-	A
			T _j =125°C	-	259	-	
			T _j =175°C	-	262	-	
Q _{rr}	Recovered charge	V _{rr} =600V I _F =300A V _{GE} = +15V/-8V	T _j =25°C	-	22.6	-	uC
			T _j =125°C	-	41.7	-	
			T _j =175°C	-	56.5	-	
E _{rr}	Reverse recovered energy	Inductive load switching operation	T _j =25°C	-	7.05	-	mJ
			T _j =125°C	-	12.7	-	
			T _j =175°C	-	17.9	-	
R _{th(j-c)}	Thermal Resistance, Junction to Case (Diode)			-	0.083	-	K/W
R _{th(c-s)}	Thermal Resistance, Case to sink (Conductive Grease applied) , Note1			-	0.10	-	K/W

Note1: Assumes Thermal Conductivity of grease is $2.8\text{W}/\text{m}\cdot\text{K}$ and thickness is $50\mu\text{m}$.

Test Conditions

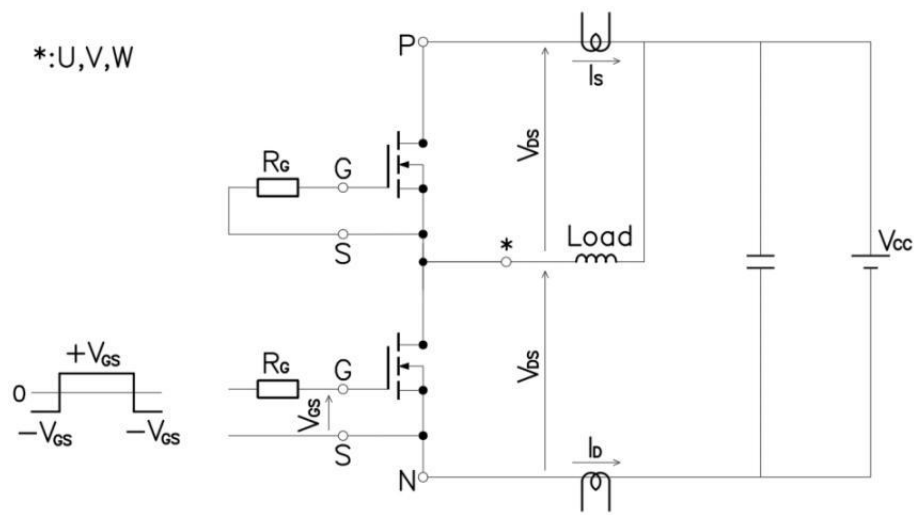


Figure 3. Switching time measure circuit

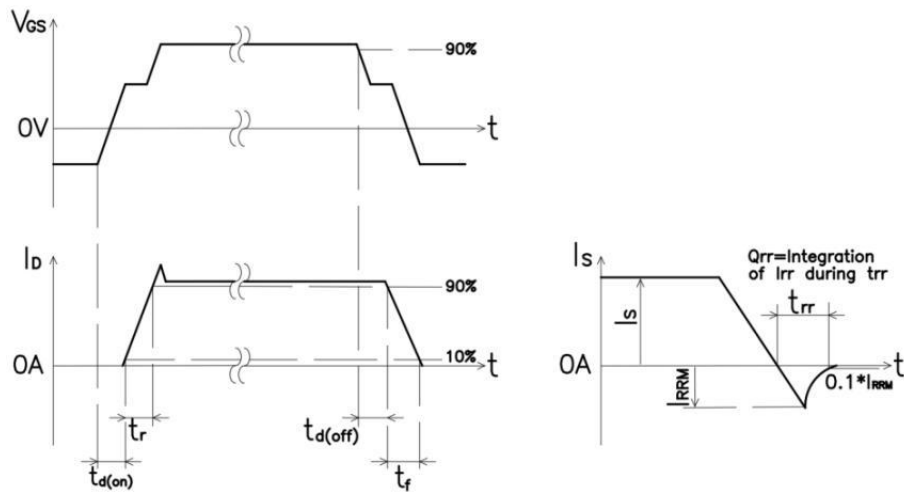


Figure 4. Switching time definition

SiC Mosfet: T2, T3

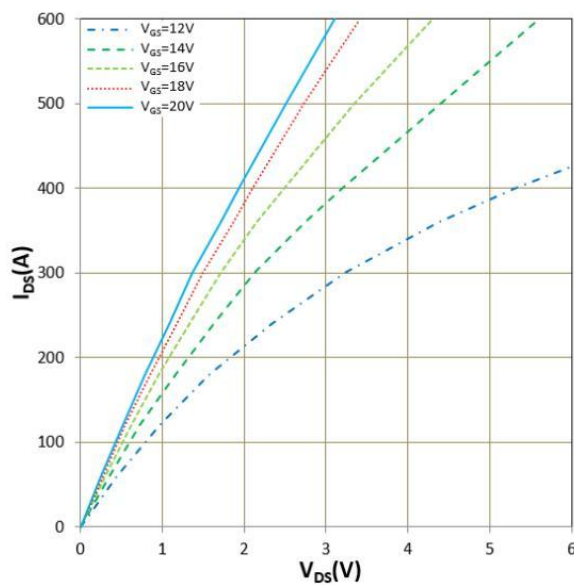


Figure 5. I_{DS} vs V_{DS}
 $T_j = 25^\circ\text{C}$

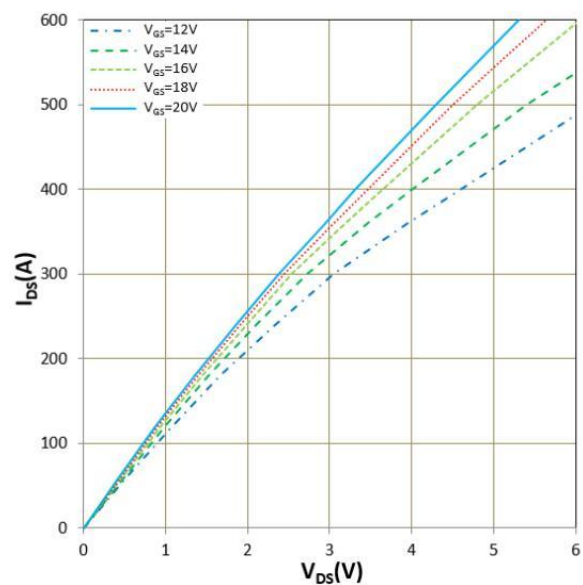


Figure 6. I_{DS} vs V_{DS}
 $T_j = 175^\circ\text{C}$

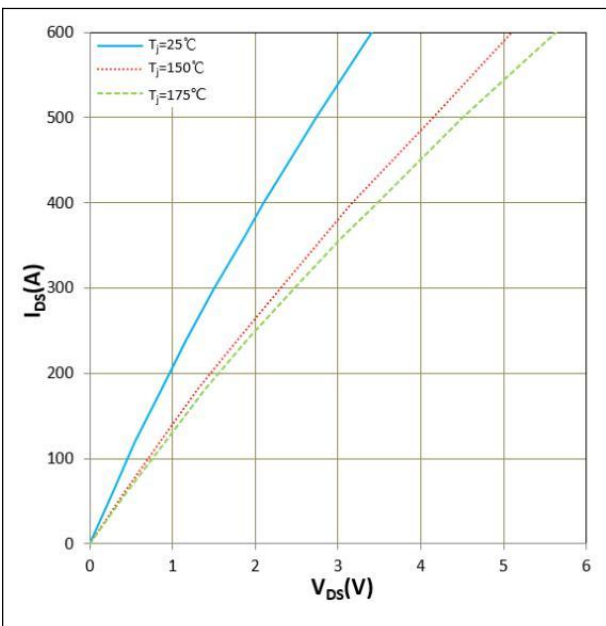


Figure 7. I_{DS} vs V_{DS}
 $V_{GS}=18V$

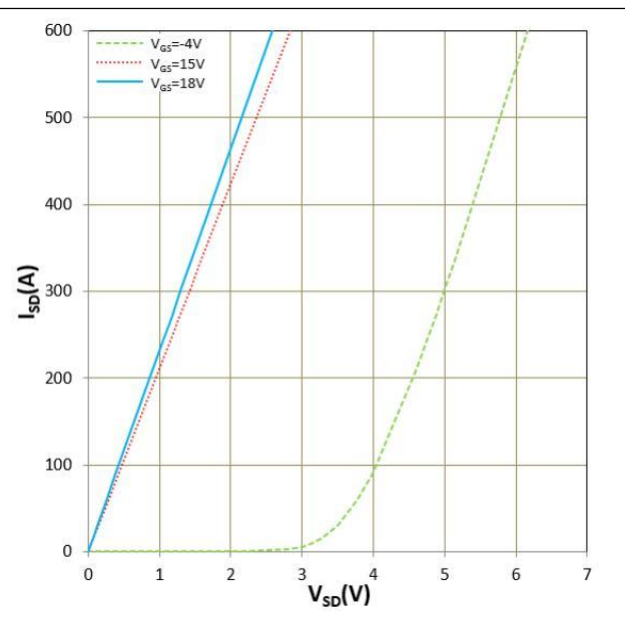


Figure 8. I_{SD} vs V_{SD} (V_F)
 $T_j = 25^\circ C$

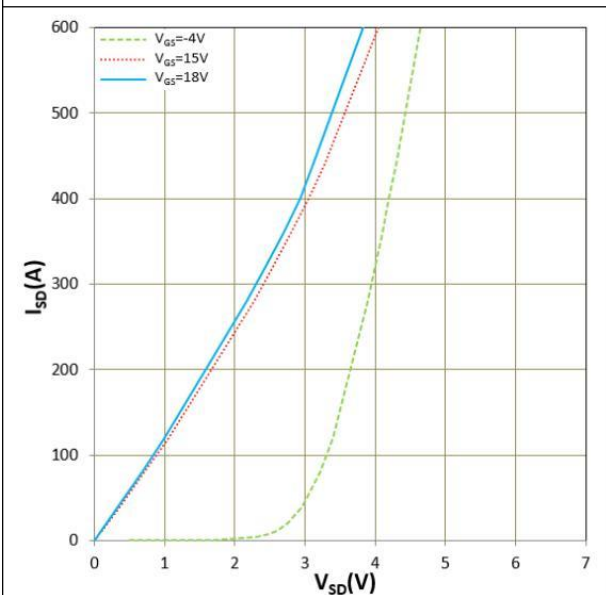


Figure 9. I_{SD} vs V_{SD} (V_F)
 $T_j = 150^\circ C$

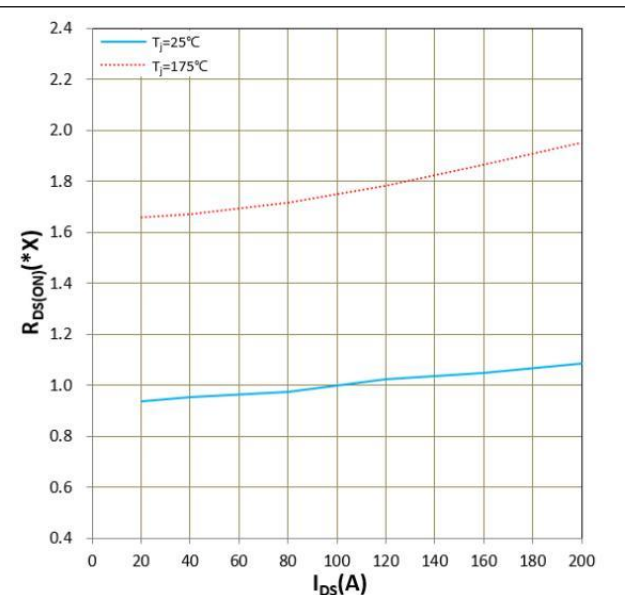


Figure 10. $R_{DS(ON)}$ vs I_{DS}
 $1.0x = 4.3m\Omega$, $V_{GS}=18V$

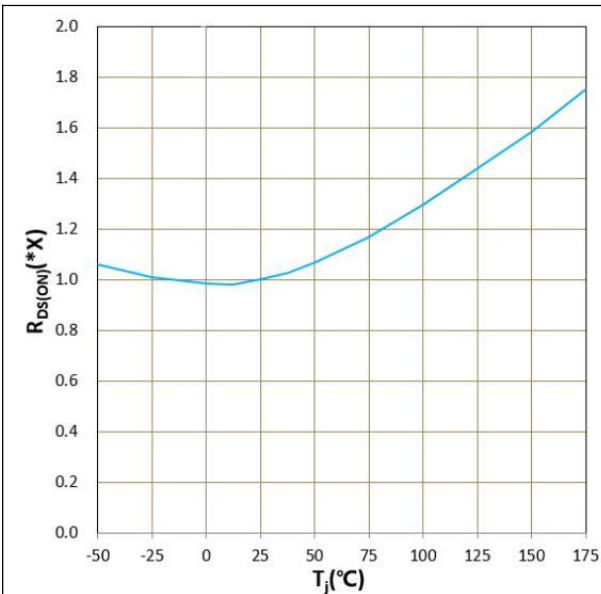


Figure 11. $R_{DS(on)}$ vs T_J
 $1.0x = 4.3m\Omega$, $I_D = 300A$

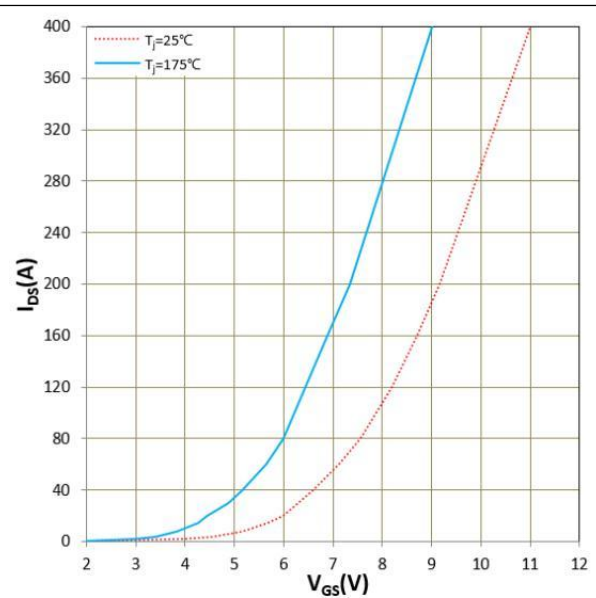


Figure 12. I_{DS} vs V_{GS}
 $V_{DS} = 10V$

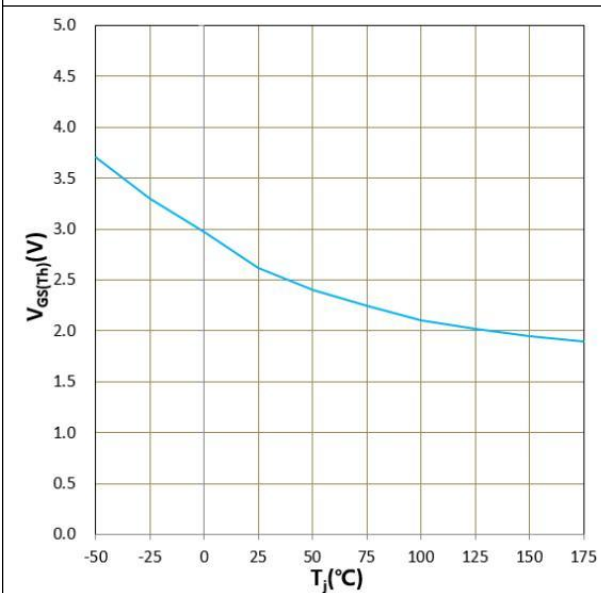


Figure 13. $V_{GS(th)}$ vs T_J
 $V_{DS} = 10V$, $I_{DS} = 80mA$

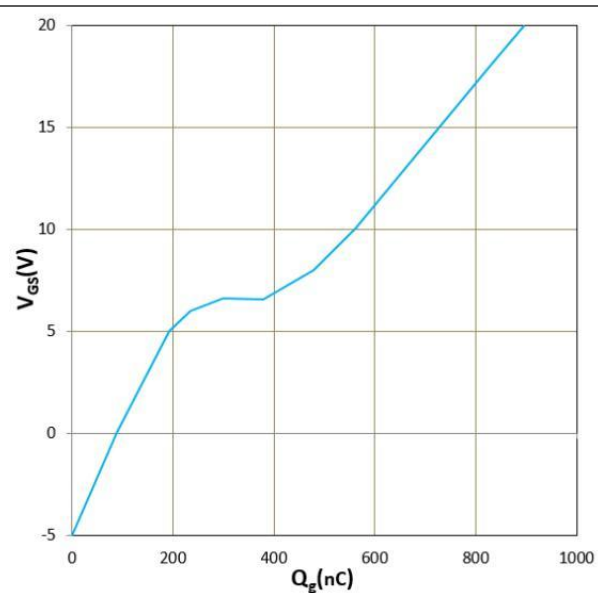


Figure 14. Gate charge
 $I_{DS} = 200A$, $I_{GS} = 0.4mA$, $V_{DS} = 400V$

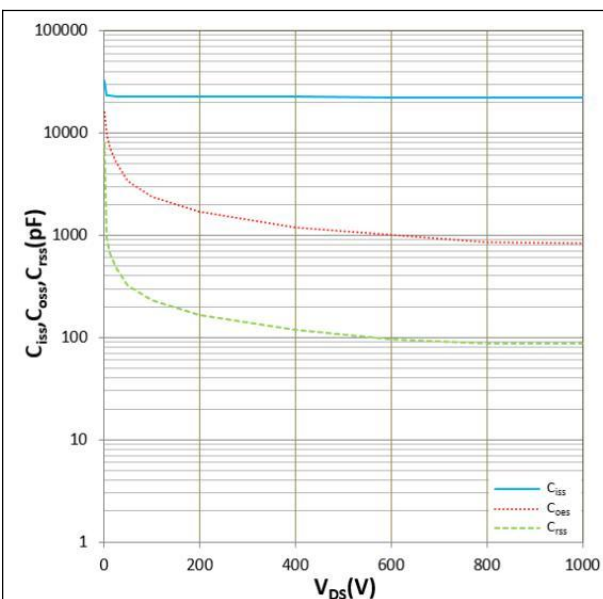


Figure 15. C_{iss} , C_{oss} , C_{rss} vs V_{CE}

$V_{AC}=25\text{mV}$, $f=1\text{MHz}$

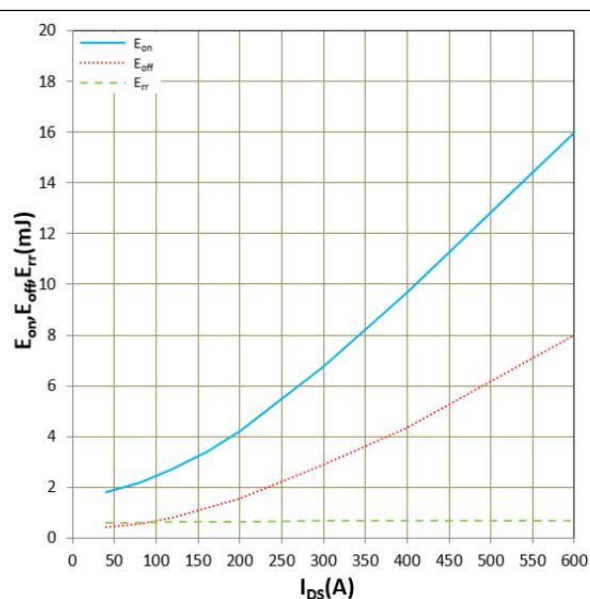


Figure 16. E_{on} , E_{off} , E_{rr} vs I_{DS}

$T_j=25^\circ\text{C}$, $V_{CC}=600\text{V}$, $V_{GE}=+15/-4\text{V}$
 $R_{GON}/R_{GOFF}=5.0\Omega$, Inductive Load

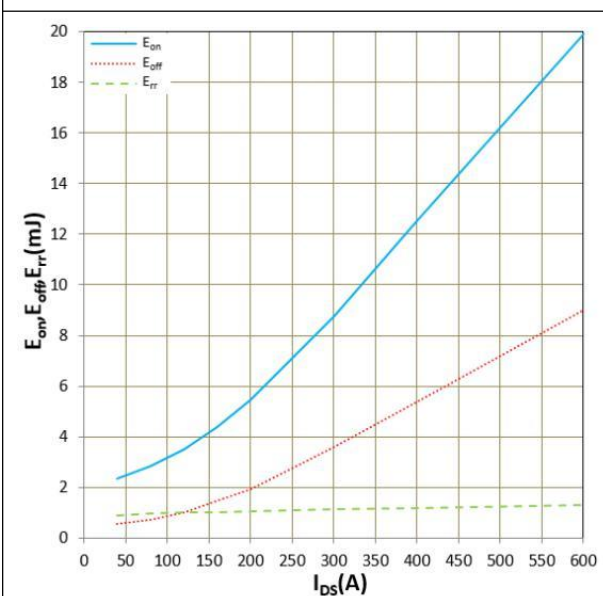


Figure 17. E_{on} , E_{off} , E_{rr} vs I_{DS}

$T_j=150^\circ\text{C}$, $V_{CC}=600\text{V}$, $V_{GE}=+15/-4\text{V}$
 $R_{GON}/R_{GOFF}=5.0\Omega$, Inductive Load

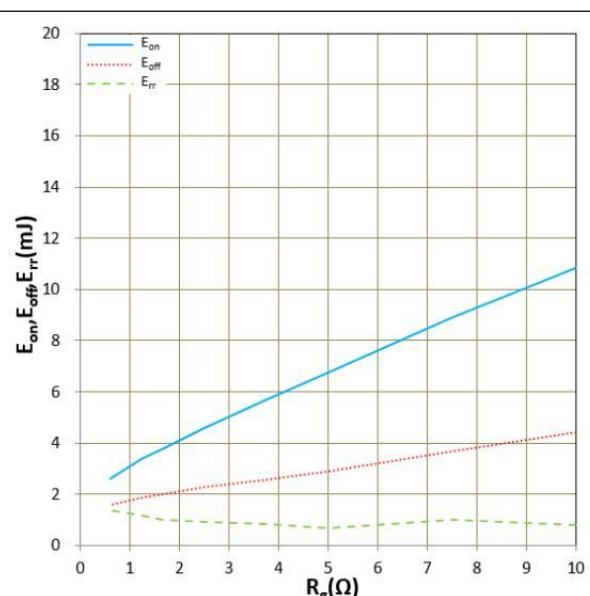


Figure 18. E_{on} , E_{off} , E_{rr} vs R_g

$T_j=25^\circ\text{C}$, $V_{CC}=600\text{V}$, $V_{GE}=+15/-4\text{V}$,
 $I_D=300\text{A}$, Inductive Load

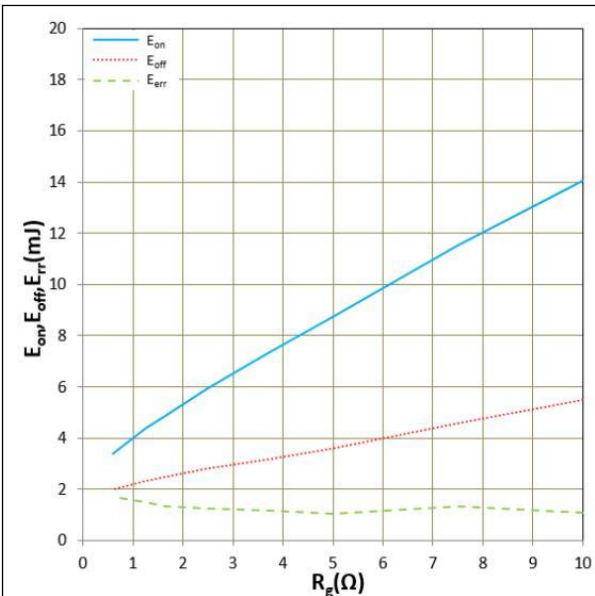


Figure 19. E_{on} , E_{off} , E_{err} vs R_g
 $T_j=150^\circ\text{C}$, $V_{CC}=600\text{V}$, $V_{GE}=+15/-4\text{V}$,
 $I_D=300\text{A}$, Inductive Load

IGBT: T1, T4, T5, T6 + Diode: D1, D4, D5, D6

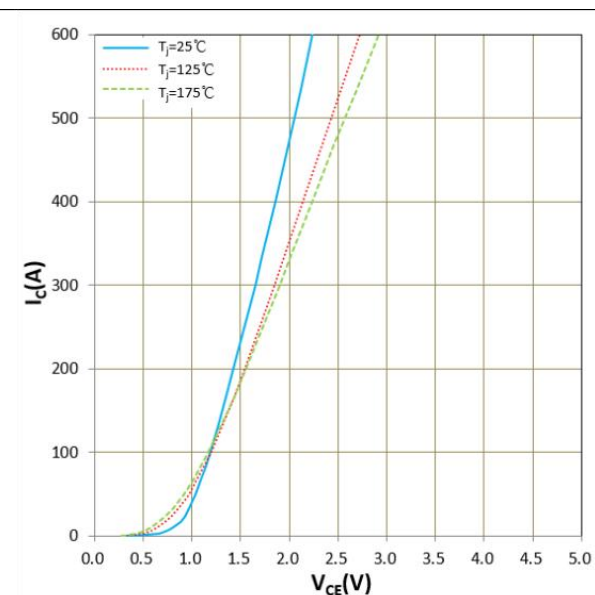


Figure 20. I_c vs V_{CE}
 $V_{GE}=15\text{V}$

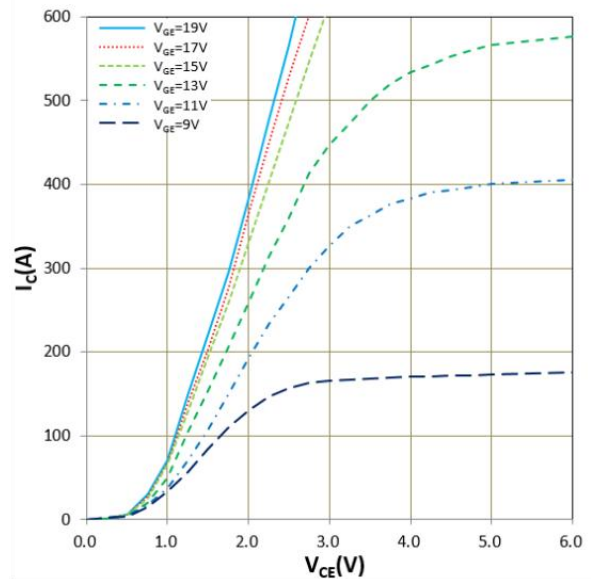


Figure 21. I_c vs V_{CE}
 $T_j=175^\circ\text{C}$

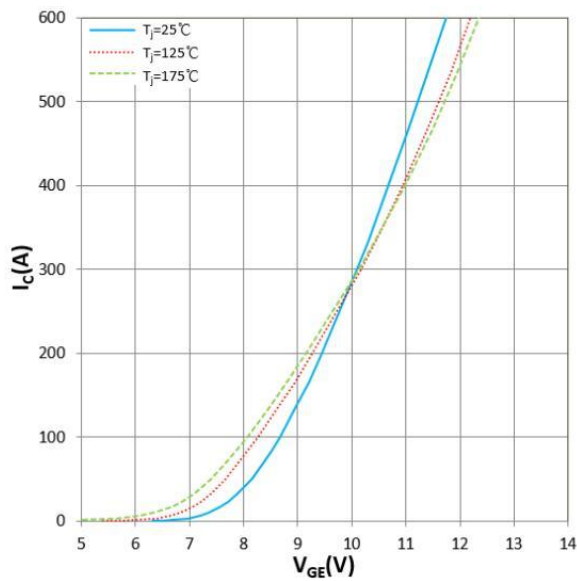


Figure 22. I_c vs V_{GE}
 $V_{CE}=20V$

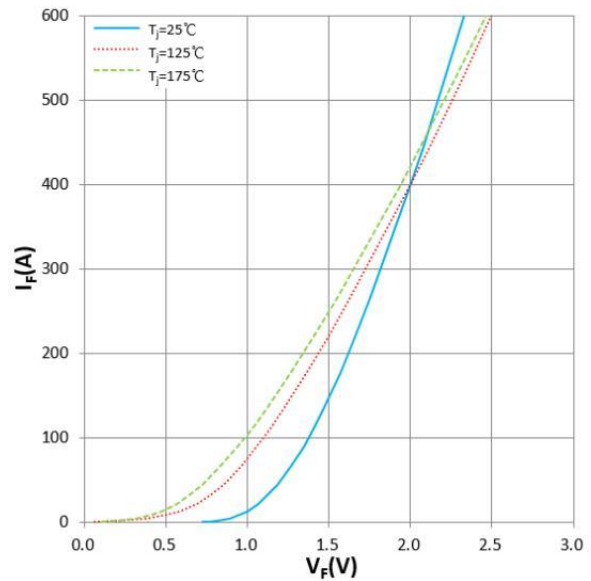


Figure 23. I_f vs V_F

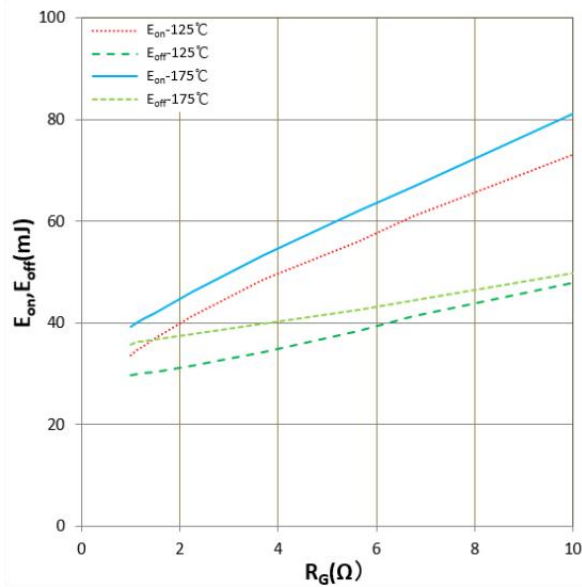


Figure 24. E_{on} , E_{off} vs R_G (Typ)
 $V_{CC}=600V$, $V_{GE}=+15V/-8V$, $I_c=300A$
Inductive Load

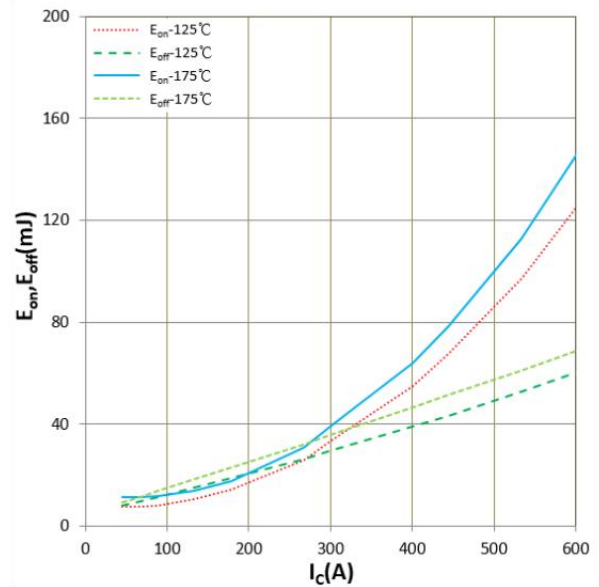


Figure 25. E_{on} , E_{off} vs I_c (Typ)
 $V_{CC}=600V$, $V_{GE}=+15V/-8V$, $R_G=1.0\Omega$
Inductive Load

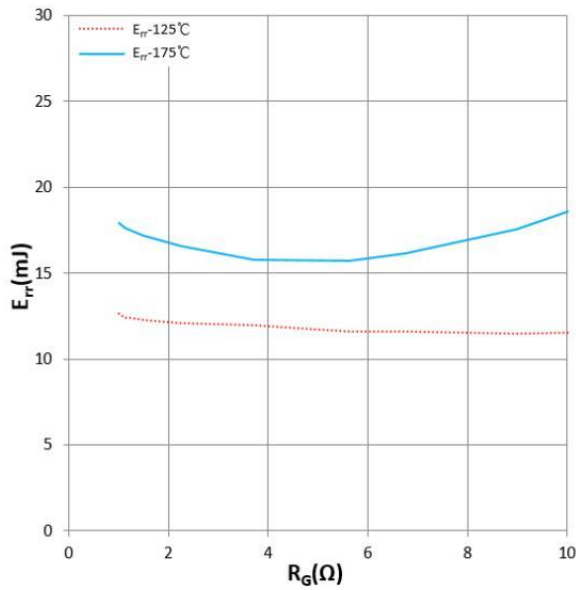


Figure 26. E_{rr} vs R_G (Typ)
 $V_{CC}=600V$, $V_{GE}=+15V/-8V$, $I_F=300A$
 Inductive Load

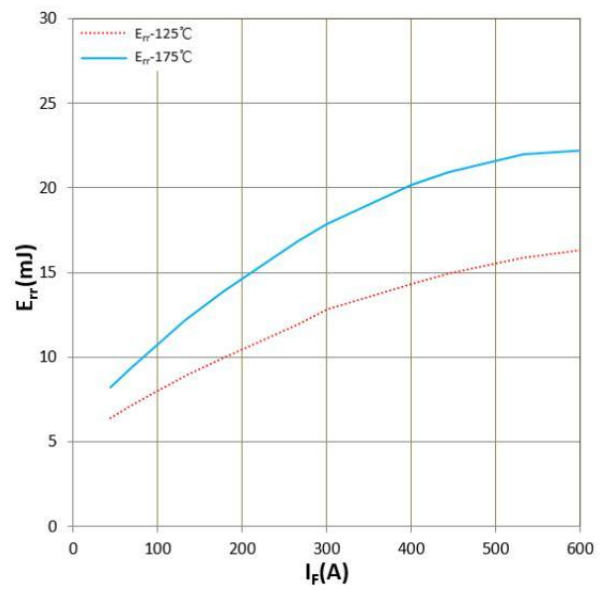


Figure 27. E_{rr} vs I_F (Typ)
 $V_{CC}=600V$, $V_{GE}=+15V/-8V$, $R_G=1.0\Omega$
 Inductive Load

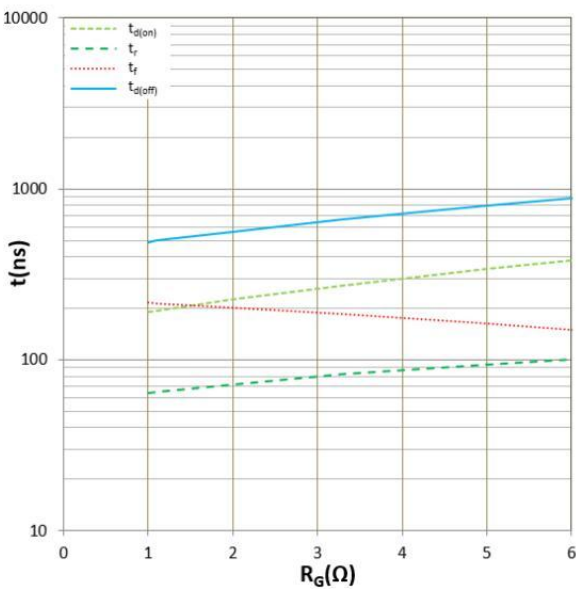


Figure 28. Switching time vs R_G (Typ)
 $V_{CC}=600V$, $V_{GE}=+15V/-8V$, $I_C=300A$
 $T_j=175^\circ C$, Inductive Load

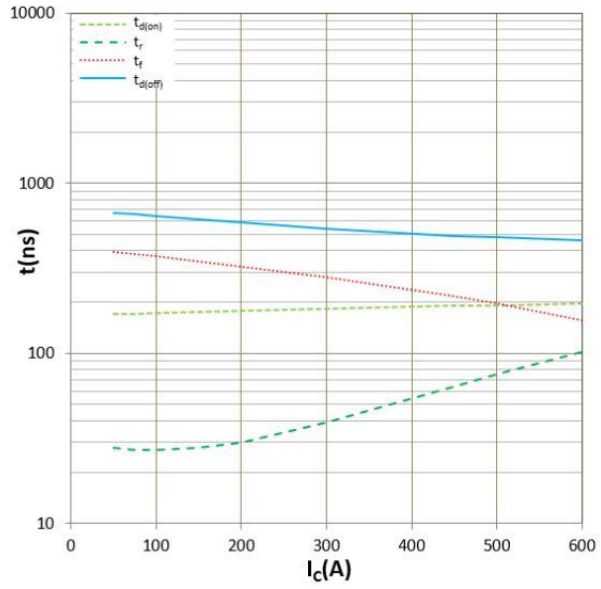


Figure 29. Switching time vs I_C (Typ)
 $V_{CC}=600V$, $V_{GE}=+15V/-8V$, $R_G=1.0\Omega$
 $T_j=175^\circ C$, Inductive Load

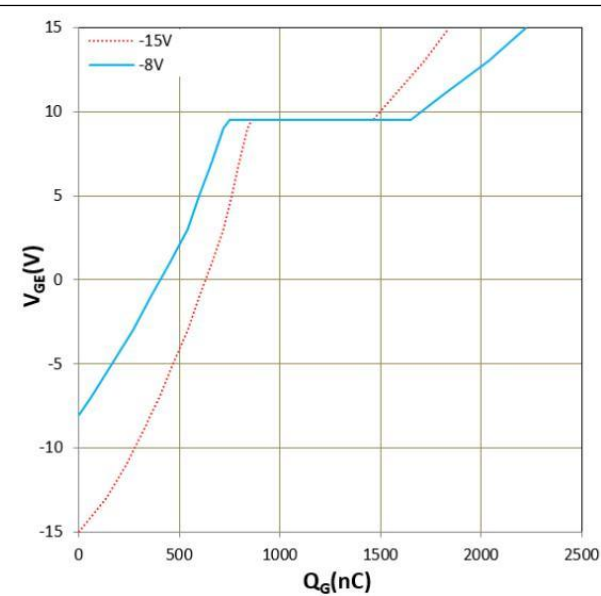


Figure 30. Gate charge

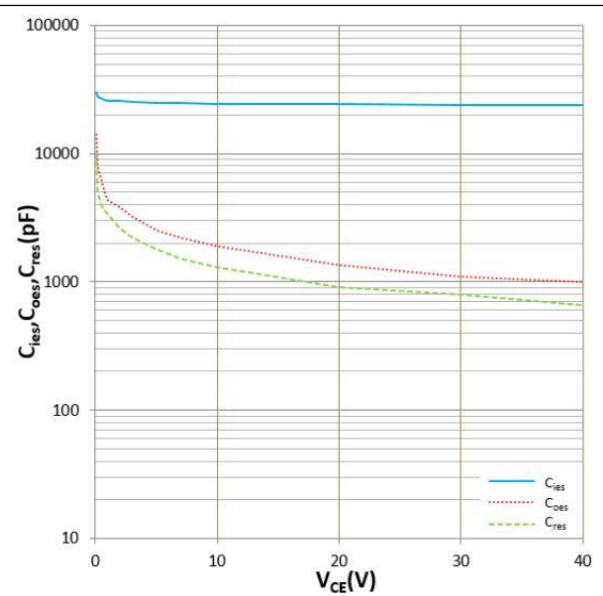


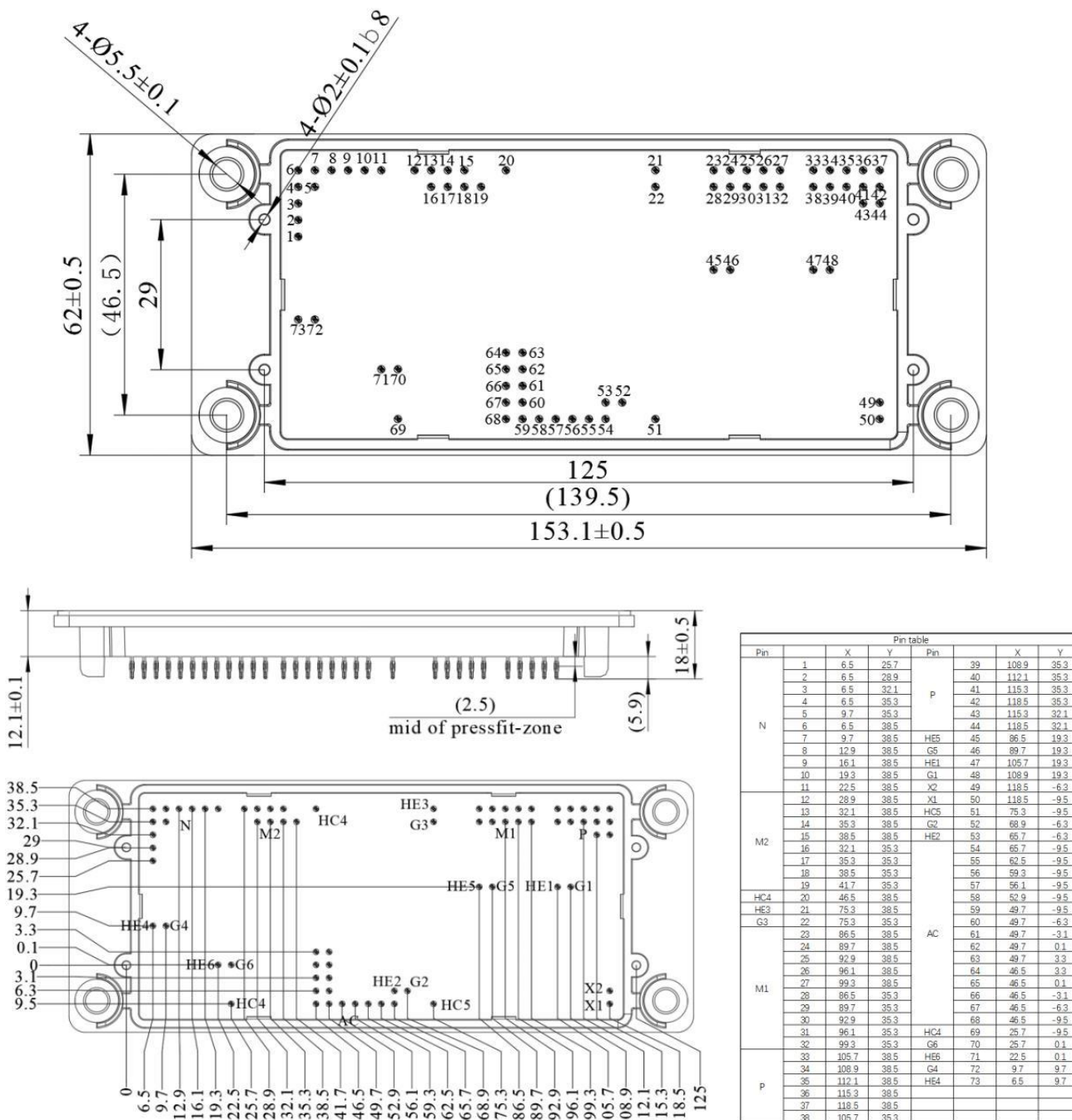
Figure 31. C_{ies} , C_{oes} , C_{res} vs V_{CE}

$T_j = 25^\circ\text{C}$, $f = 100\text{KHz}$

Preliminary datasheet _Ver.A EN

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Package dimensions



IMPORTANT NOTICE

This product data sheet describes the characteristics of this product for which a warranty is granted. Any such warranty is granted exclusively under the terms and conditions of the supply agreement. There will be no guarantee or of any kind for the product and its characteristics.

The data contained in this document is exclusively intended for technically trained staff. You and your technical departments will have to evaluate the product's suitability for the intended application and the completeness of the product data concerning such application.

Due to technical requirements, our product may contain dangerous substances. For information on the types in question, please contact the sales staff responsible for you.

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